NEPCON WORLD JAPAN

SMT TESTING IC PACKAGING COMPONENTS PCB/PWB LASER

Post Show Report 2009

Table of Contents

Feb. 6, 2009 <For immediate release>

Exhibition Outline 2009

38th INTERNEPCON JAPAN

26th ELECTROTEST JAPAN

2nd LASER & OPTICS 2009 EXHIBITION / CONFERENCE

ICP 10th IC PACKAGING TECHNOLOGY EXPO

10th INTERNATIONAL ELECTRONIC COMPONENTS TRADE SHOW ELE TRADE 2009 Custom-made / Technical Consultation / Components Procurement

10th PRINTED WIRING BOARDS EXPO PWB EXPO PWB / PCB Material EMS CAD Tool

1st Int'l Automotive Electronics Technology Expo CAR-ELE JAPAN Components Testing Embedded Technology Equipment In-vehicle System

Dates: **January 28 (Wed) – 30 (Fri), 2009**
10:00-18:00 (10:00-17:00 on Jan. 30)
Venue: **Japan, Tokyo Big Sight**
Organised by: Reed Exhibitions Japan Ltd.

ASIA'S LARGEST exhibition for electronics manufacturing!

Being Asia's largest exhibition for electronics design, R&D and manufacturing, NEPCON WORLD JAPAN again concluded with a great success. Consisting from the 7 exhibitions (see below for the details of each exhibition), it was held from January 28 (Wed) – 30 (Fri) at Tokyo Big Sight, Japan. In addition to 6 different exhibitions inside NEPCON WORLD JAPAN held annually, new exhibition, 1st Int'l Automotive Electronics Technology Expo (CAR-ELE JAPAN) celebrated its launch this year. The fair was given positive ratings by almost all exhibitors, visitors, and press members. Altogether, **60,271 visitors (increased by 9.9% from the previous year)** made their way to Tokyo for NEPCON WORLD JAPAN where they encountered **1,228 exhibitors** with the latest and innovative technologies of the industry. Especially, newly launched CAR-ELE JAPAN drew a huge attention from the exhibitors, visitors and media despite the difficult circumstances which automotive industry is facing worldwide. One of the exhibitors of CAR-ELE JAPAN, TOBII TECHNOLOGY JAPAN CO., LTD. said "The pamphlets gone out during the first day because the visitors to our booth were far more than which we expected! We are overwhelmed with the result and proudly to say CAR-ELE JAPAN is the best in gathering the visitors than any other industry event which we had exhibited. We anticipate greatly for the business to be born from here."

NEPCON WORLD JAPAN is known as the perfect venue for providing a very important opportunity as exhibitors show new technologies and products, and offering the users the latest innovations. For product development and cutting cost, these technologies hold enormous promises. Also, Show Director Kenji Okabe commented that "We had been receiving thousands of visiting inquiries months prior to the show not only from all across Japan but also from around the world especially from Korea, China and Taiwan. Most of the industry professionals visit NEPCON WORLD JAPAN to carry out their purchasing plans.” Because both exhibitors and visitors know that business chances are everywhere, great numbers of business meetings were held almost at every stand in the venue concluding NEPCON WORLD JAPAN with billion dollars contracts. Also, the increasing number on visitors for 9.9% from the previous year shows the great anticipation from throughout the industry that NEPCON WOLRD JAPAN is the must visit event of the year.

38th INTERNEPCON JAPAN

INTERNEPCON JAPAN celebrated its 38 consecutive years. It is Asia’s largest exhibition featuring all kinds of equipment, materials and technologies for electronic manufacturing and SMT. Due to tighter environmental standards like RoHS, REACH, and EuP are proceeding internationally, lead-free Soldering machines gained great attentions this year. In particular, soldering materials/flux which is low-priced and high-credibility was notable inside Soldering Zone reflecting the time. Furthermore, two new zones “Cleaning Equipment & Cleaners Zone” and “EMS/Contract Manufacturing Zone” were always crowded by the visitors.

10th INTERNATIONAL ELECTRONIC COMPONENTS TRADE SHOW

All kinds of Electronic Components and Devices for consumer electronics, communications, automotive electronics, and many more were exhibited. This year, new topics such as newly launched Sensor Zone and Connector & Cable Zone gained recognitions from the visiting professionals. On the other hand, under the basic and the most important concept “the place to have business” of this exhibition, each exhibitor were acquiring the ‘sample orders’ proactively from the visitors with their plans, hoping to have solutions. Furthermore, approaches of the visitors looking for the solutions at ELE TRADE were clearly seen under the situation of the users restructuring the procurement in zero-base.

10th PRINTED WIRING BOARDS EXPO

Japanese and international exhibitors featured all kinds of printed wiring boards, modular board, design services, CAD tools and many more. Advancement is constantly achieved and printed wiring boards are evolving in recent years making electronic components to small, thin, lightweight, high-speed, and multifunctional. Specifically, built-in parts gained a great attention as its high anticipation for loading on the mobile products. This technology was exhibited by CMK Corporation, Dai Nippon Printing, Clover Electronics. They gathered a huge attention from the visitors.

2nd LASER & OPTICS 2009

Innovative optical technologies/services featuring industrial laser machines and optical components were exhibited. Show venue was packed with excitement by the seriousness of the visitors along with the wave of laser processing in electronic industries. Laser, gaining the recognition more than that of last year, many visitors brought sample materials with them asking exhibitors to demonstrate the work. Also, not only visitors gathered to laser processing but also to the exhibitors with laser oscillators (light sources) and optical components. Many consultations were seen where visitors looking for the best light source of there needs and power outputs.

26th ELECTROTEST JAPAN

It is Japan's largest exhibition, specialised in test and inspection in electronics manufacturing and R&D. With the keyword of low-priced, high-quality and high-efficiency on production site, each exhibitor displayed the new products/technologies having reflected the economic situations. Visitors listened to the business solutions presented from the exhibitors seriously and more business discussions were held everywhere than previous years. Especially, there were numbers of exhibitors proposing the efficiency improvement on cell production and line design. ELECTROTEST JAPAN this year was not only the place for new products and technologies but also became the place to have business discussions taking one step further.

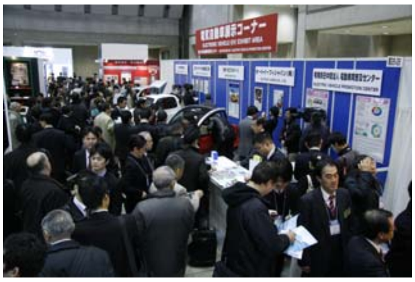
10th IC PACKAGING TECHNOLOGY EXPO

The importance of the packaging technology is increasing as a point of the differentiation of the semiconductor. The latest IC final manufacturing and packaging technology for sensors, MEMS devices, opto devices gathered in this Expo being Japan's most powerful exhibition specialised in this industry.

NEW

1st Int'l Automotive Electronics Technology Expo (CAR-ELE JAPAN)

As the first ever trade show in Japan for the industry, CAR-ELE JAPAN grandly launched from this year. It is an international exhibition gathering all kinds of in-vehicle systems, components/materials and manufacturing equipment related to automotive electronics. Professionals of this industry, including automobile/automotive electronics system manufacturers used the venue for a comparative review of the latest technologies and innovations for their product installations. Also, the Show Management held an *Electronic Vehicle (EV) Exhibit Area*. This highlighted area not only gathered attention from the exhibitors and visitors but also from various media. One of the Japanese most famous news programs at NHK (Japan Broadcasting Corporation) made the news on the morning of the first day of the show as well as many other press members visited the area to make the report on the latest technologies of the Electronic Vehicle.



General Statistics

Exhibitors

Number of Exhibitors

1,228 exhibitors

Visitors

Number of Visitors

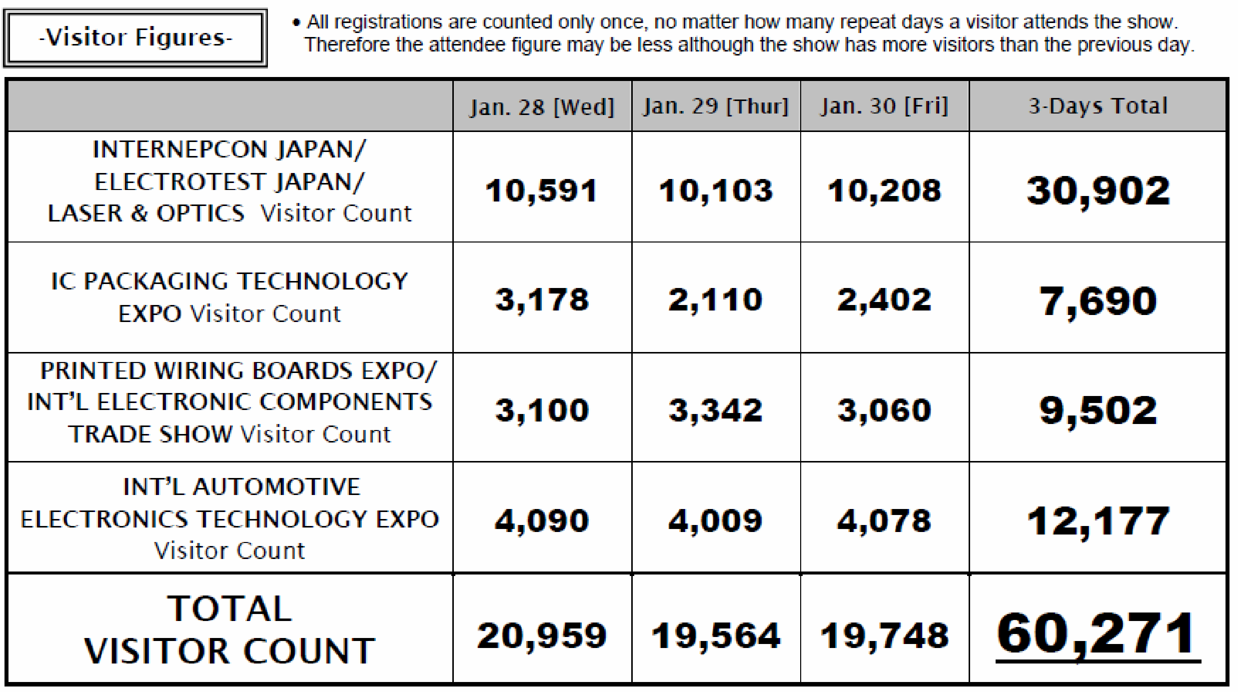
60,271 trade visitors

Principles of Perspective

- We consider that announcing an accurate number of visitors is an obligation to exhibitors.
- We consider that overstating the number is a fraud act, and also a false advertisement.
- Shortly after the exhibition, we will announce the total number of visitors in writing with clear notification based on our “Visitor Counting System”.

Principles of Visitor Counting System

- Only those who visited the exhibition and completed registration on-site are counted.
- All registrations are counted only once, no matter how many repeat days/times a visitor attends the exhibition.
- We consider that the way above is the most rigorous and accurate numeration. Counting the numbers at the entrance every time leads to overstated figures, and Reed Exhibitions Japan Ltd. will not adopt that sort of numeration.



-Visitor Figures-

- All registrations are counted only once, no matter how many repeat days a visitor attends the show. Therefore the attendee figure may be less although the show has more visitors than the previous day.

	Jan. 28 [Wed]	Jan. 29 [Thur]	Jan. 30 [Fri]	3-Days Total
INTERNEPCON JAPAN/ ELECTROTEST JAPAN/ LASER & OPTICS Visitor Count	**10,591**	**10,103**	**10,208**	**30,902**
IC PACKAGING TECHNOLOGY EXPO Visitor Count	**3,178**	**2,110**	**2,402**	**7,690**
PRINTED WIRING BOARDS EXPO/ INT’L ELECTRONIC COMPONENTS TRADE SHOW Visitor Count	**3,100**	**3,342**	**3,060**	**9,502**
INT’L AUTOMOTIVE ELECTRONICS TECHNOLOGY EXPO Visitor Count	**4,090**	**4,009**	**4,078**	**12,177**
TOTAL VISITOR COUNT	**20,959**	**19,564**	**19,748**	**60,271**

Complete details of the visitor figures can also be obtained from >>>http://www.nepconworld.jp/en/doc/NWJCAR09_TAC.pdf

Exhibitor Comments

The quality of the buyers produced the high satisfactions from the exhibitors. Here are some of the voices gathered to the Show Management during the fair.

EO TECHNICS CO., LTD. (Korea)

"We received 10 inquiries from the potential customers during the show. We were able to promote our new products effectively and found agent/distributor in Japan as well. In addition to that, Show Management support were professional and we found their exhibitor manual very useful. Also we strongly felt that NEPCON WORLD JAPAN delivers new leads and higher quality leads than any other sales or marketing options. We are satisfied with the results gained through exhibiting this year and we will come back again next year!"

YAMASHITA MATERIALS CORP. (Japan)

"Those who came to our booth have increased in 10% compared to last year. Also we have impression that more visitors came with specific tasks linking to the business than that of ordinary years. We already submitted 2 estimations, expecting several million JPY orders in the end."

ASTI CORPORATION (Japan)

"There were over 100 negotiations and 70 of those were concrete inquiries. We felt that this year's leads were more concentrated than we had in past years. There were numbers of inquiries on Soldering Machine (18 million JPY) and we already visited 4 companies for the meetings in 4 days after the show. We are coming back to NEPCON WORLD JAPAN 2010."

Concurrent Event

■ IC Packaging Technology Expo VIP Reception Party

Gathering top leaders and executives, the VIP Reception Party was grandly held. Keynote speaker, Mr. Shozo Saito, President and CEO of Toshiba Semiconductor Company made a toast. After saying that he was very surprised to see a huge audience to his session, he concluded, "As you all know, the semiconductor industry is now facing a difficult time with unknown future consequences. But as I mentioned in my Keynote speech, Toshiba will be enhancing technical development to break through and advance. In this sense, this exhibition is a very important opportunity for us and I look forward to the continuous support from all those present here today." Each attendees of this party took advantage of the evening to expand/renew the network and exchanged the information.

Technical Conferences

One of the biggest events attracting many industry professionals were the technical conferences held alongside of the shows. **51 sessions** were held as NEPCON WORLD JAPAN conference, by world's top leaders. Total of **5,913 professionals** participated to collect the industry's latest information and technologies. See below for the keynote sessions conducted for each exhibition.

INTERNEPCON/ELECTROTEST Keynote Session

Dawn of Printed Electronics World

Katsuaki Suganuma
Professor, Director of Nanoscience and Nanotechnology Center, The Institute of Scientific and Industrial Research (ISIR), Osaka University

Abstract: Electronics production technology using printing is currently gaining attention around the world. (It is the new technology of mass and high-speed production system to make of electronic parts.) The product group covered by this technology is extremely broad. The lecture introduced printed electronics technologies where nanotechnology is being applied to carve out a new world.

Future Prospects for the Photovoltaic Power Generation and the Packaging Technology of the Solar Cells

Yukinori Kuwano
President, Photovoltaic Power Generation Technology Research Association

Abstract: The presentation discussed the latest trends and future outlook of solar power generation which is ultimately capable of solving the problems of energy and environmental disruption, which have become issues for all mankind. Solar power generation today is facing a low-cost issue. Meanwhile, providing a longer life to solar cell modules greatly contributes to cost reduction in solar power generation. Challenges of mounting technology related to these issues and potential solutions were discussed.

IC PACKAGING TECHNOLOGY EXPO Keynote Session

Honda Electronics Technologies to Support Evolution of Honda Intelligent Product –Realizing Eco-Friendly and Safety Car with Higher Performance-

Toyohei Nakajima
Senior Chief Engineer, Senior Manager, Honda R&D Co., Ltd.

Abstract: The presentation introduced Honda's present and future-oriented technologies for the environment and safety required in automobiles today, and explained trends in car electronics that are vital for achieving these technologies and Honda's commitment for supporting automotive electronic control systems that are continuing to become more functional and larger in scale.

Toshiba's Semiconductor Strategy -The Semiconductor Packaging Strategy-

Shozo Saito
Corporate Senior Vice President, President and CEO, Semiconductor Co., Toshiba Corp.

Abstract: The lecture explained Toshiba's semiconductor business, driven by the three pillars of memory, system LSI and discrete components, focusing on the product and semiconductor packaging strategy that will drive its success, as well as its high expectations for packaging technology.

PRINTED WIRING BOARDS EXPO Keynote Session

Sharp's Communication Strategy Toward a Ubiquitous Society

Masafumi Matsumoto
Representative Director and Executive Vice President, Sharp Corp.

Abstract: New businesses and services are being created by "Digital Convergence", the digital network integration of communication, information and visual equipment. Sharp is aiming to "enable a true ubiquitous society with the world's No.1 LCD (Liquid Crystal Display)" by introducing a new lifestyle enabled by the integration of services and networks with our series of display-equipped products such as LCD TVs and mobile telephones. The session presented Sharp's initiatives toward a ubiquitous society, focusing on the telecommunication business.

Development of Intelligent Robots and the Future Developed by Science and Engineering

Hiroshi Ishiguro
Professor, Dept. of Adaptive Machine Systems, Graduate Schools of Engineering, Osaka University

Abstract: The lecture examined a relatively new field of research in robots, the series of research regarding robots relating to humans, as well as research on biomimetic robots, which suggest the future direction of science and technology. Regarding research on robots relating to humans, the presenter talked about a one-of-a-kind android research and its potential. Regarding biomimetic robots, which is on the future path of these existing research projects, the direction for new production methods and creation of systems based on the same principles as living organisms was discussed.

CAR-ELE JAPAN Keynote Session

Towards a Sustainable Automotive Industry
-The Future of Power Electronics and Information Technology-

Takashi Shigematsu
Managing Officer, Toyota Motor Corp.

Abstract: The automotive electronics industry is experiencing a great change, facing environmental issues and the depletion of resource and energy. It is required to explore the new technology to meet the needs of the age. The speech proposed the future of the industry while focusing on power electronics and information network.

ContiGuard® -Safety Technologies Today and Tomorrow

James Remfrey
Director, Technology Intelligence, Chassis & Safety, Continental

Abstract: The networking of active and passive safety (ContiGuard®) is the fundamental basis for comprehensive vehicle safety. Situation-relevant information relating to driver reactions, vehicle behavior and traffic environment are fed into a crash probability calculator, which continually assesses the current crash risk and intervenes when necessary with appropriate measures to avoid a crash and reduce potential injuries. ContiGuard® provides effective protection not only for vehicle occupants but also for other, vulnerable road users. This paper describes the current status in the functional potential attained by networking active and passive safety systems (ContiGuard®), the integration of surrounding sensors and introduces the next ultimate step towards global vehicle and traffic safety - telematics.

Automotive Industry Faces Unknown Business Environment
-Key Point to Survive is Environmental Technology and Production Revolution-

Noriyuki Matsushima
Managing Director, Equity Research, Nikko Citigroup Ltd.

Abstract: The global automotive industry is gradually affected by the worldwide recession caused by the financial crisis in the U.S. and Europe. The speech was to detail low-cost commercial applications of environmental technology and importance of manufacturing innovations as the keys to survive in the economy with slower demands, while discussing world economic reconstruction.

For more details of the seminar refer to >>> http://www.nepconworld.jp/en/conference/

Next Show 2010

Applicants Rushing in for 2010 Exhibition Spaces

With its end with a great success, anticipation for next year's show is already building like never before for NEPCON WORLD JAPAN. Most of the exhibitors have signed up to participate again next year during the show period, as well as numbers of new companies. Next year's show will be definitely not to be missed, mark your calendar now and save your date for January 20 (Wed) – 22 (Fri), 2010 for upcoming shows.

Schedule for NEPCON WORLD JAPAN 2010

Dates: January 20 (Wed) – 22 (Fri), 2010

Venue: Japan, Tokyo Big Sight

For more information, please contact **NEPCON WORLD JAPAN Show Management**:
Attn: **Satoko Hombu (Ms.), Hajime Suzuki (Mr.), Chisato Miyawaki (Ms.)**
Tel: **+81.3.3349.8502** Fax: **+81.3.3349.4900** E-mail: **inw@reedexpo.co.jp**
Web: **http://www.nepconworld.jp/en/**